

Amendments of the Claims

The following list of claims replaces all previous version(s) of claims.

1 -7. Canceled.

8. (currently amended) A method of forming a patterned material structure on a substrate, said method comprising:

(A) providing a substrate with a layer of said material wherein said material is chromium-containing metal composition,

(B) applying a resist composition to said substrate to form a resist layer on said substrate, said resist composition comprising

- a) an imaging polymer,
- b) acid-labile moieties,
- c) a radiation-sensitive acid generator, and
- d) a base additive component, wherein said base additive component comprises:

(i) a room temperature solid base selected from the group consisting of aromatic amines and imidazoles, and

(ii) a liquid low vapor pressure base selected from the group consisting of triethanolamine, 1-naphthylamine, 2-naphthylamine, diphenylamine, acetanilide, 3,6,9- triazaundecamethylenediamine, and 4,4'-propane-1,3-diylbismorpholine, and 1,8-azabicyclo[4.3.0]oct-5-ene,

(C) patternwise exposing said substrate to electron beam radiation whereby acid is generated by radiation-sensitive acid generator in exposed regions of said resist layer,

- (D) developing a patterned resist structure in said resist layer by removing radiation-exposed portions of said resist, and
- (E) transferring resist structure pattern to said material layer by removing portions of said material layer through spaces in said resist structure pattern.

9. Canceled.

10. (original) The method of claim 8 wherein said acid-labile protecting group is a moiety selected from the group consisting of ketals, acetals and orthoesters.

11. (original) The method of claim 8 wherein said transfer of step (F) comprises reactive ion etching.

12. (original) The method of claim 8 wherein at least one intermediate layer is provided between said material layer and said resist layer, and step (E) comprises etching through said intermediate layer.

13. (original) The method of claim 8 wherein said resist is thermally treated between steps (C) and (D).

14 - 19. Canceled.